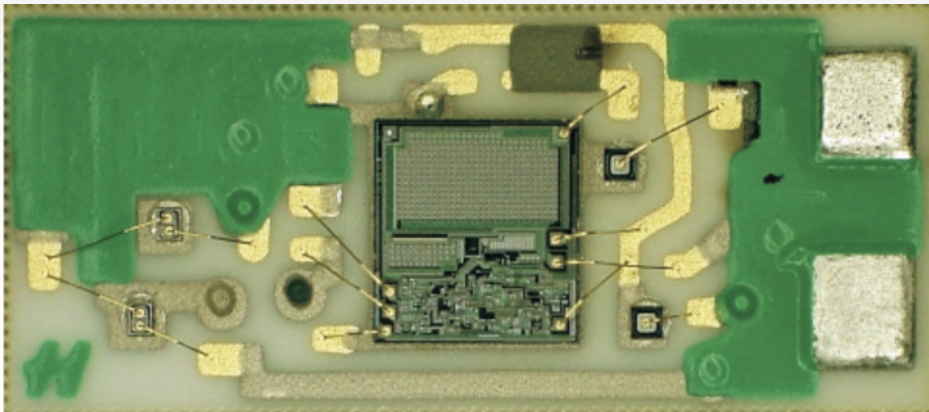


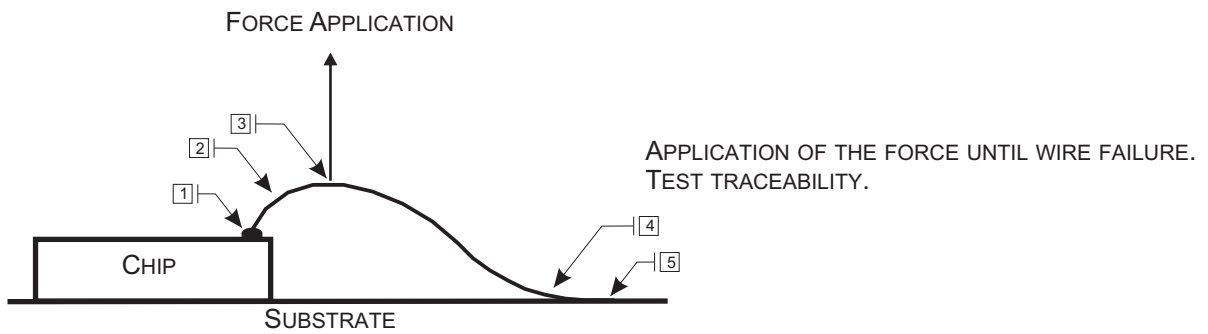
**HYBRID SA** IS ABLE TO WIRE BOND THE BARE CHIPS. SPECIFIC KNOWLEDGE OF TRAINED PERSONAL AND MODERN MACHINERY ALLOWS THE EXECUTION OF COMPLEX AND HIGH DENSITY BONDING PLAN.(CHIP TO CHIP, CHIP ON CHIP, ETC...)

DIAMETER : STANDARD 17 $\mu$ m - 33 $\mu$ m

## GOLD WIRE BONDING (BALL BONDING)



## PULL TEST



## ALUMINIUM WIRE BONDING (WEDGE BONDING)

